#### PATENT ASSIGNMENT

# Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Yoshiaki KUDO	10/26/2009
Takashi HAKODA	10/26/2009
Kiyoshi NAKAMURA	10/26/2009
Susumu MOROZUMI	10/26/2009

#### **RECEIVING PARTY DATA**

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State/Country:	JAPAN	
Postal Code:	389-0693	

## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12610869

#### **CORRESPONDENCE DATA**

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ATTORNEY DOCKET NUMBER:	MIRAI-1001
NAME OF SUBMITTER:	Ken Yoshida

Total Attachments: 3

PATENT REEL: 023752 FRAME: 0979 JP \$40.00 12610869

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> PATENT REEL: 023752 FRAME: 0980

**DOCKET NO.: MIRAI-1001** 

Nissei Ref. No.: SD610 Mirai Ref. No.: SINF0111 PATENT

### **ASSIGNMENT**

WHEREAS, We, Yoshiaki KUDO, having an address at NISSEI PLASTIC INDUSTRIAL CO., LTD., 2110, Oaza Minamijo, Sakaki-machi, Hanishina-gun, Nagano-ken, 389-0693 JAPAN, and Takashi HAKODA, having an address at NISSEI PLASTIC INDUSTRIAL CO., LTD., 2110, Oaza Minamijo, Sakaki-machi, Hanishina-gun, Nagano-ken, 389-0693 JAPAN, and Kiyoshi NAKAMURA, having an address at NISSEI PLASTIC INDUSTRIAL CO., LTD., 2110, Oaza Minamijo, Sakaki-machi, Hanishina-gun, Nagano-ken, 389-0693 JAPAN, and Susumu MOROZUMI, having an address at NISSEI PLASTIC INDUSTRIAL CO., LTD., 2110, Oaza Minamijo, Sakaki-machi, Hanishina-gun, Nagano-ken, 389-0693 JAPAN, hereinafter referred to as "the Assignor(s)", are the inventors of certain inventions or improvements for which we have made application for Letters Patent to the United States, identified as Attorney Docket No. MIRAI-1001, and entitled, "METHOD OF SETTING MOLD CLAMPING FORCE OF INJECTION MOLDING MACHINE", filed on November 2, 2009 under US Patent Application No. 12/610,869

1/8/10 1/24 Peg No 37009

WHEREAS, NISSEI PLASTIC INDUSTRIAL CO., LTD., hereinafter referred to as the assignee, having a place of business at 2110, Oaza Minamijo, Sakaki-machi, Hanishina-gun, Nagano-ken, 389-0693 JAPAN, a corporation of Japan, is desirous of acquiring the entire right, title and interest in and to the said inventions or improvements and in and to the said application, and in, to and under any and all Letters Patent which may be granted on or as a result thereof in any and all countries:

NOW, THEREFORE, for and in consideration of the sum of One Dollar (\$1.00) to each of us in hand paid by said assignee, and other good and valuable consideration, the receipt of which is hereby acknowledged, We, the said assignors, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over to said assignee, the entire right, title and interest in and to said inventions or improvements and said applications including the right to claim priority to the applications in any foreign application entitled to claim such priority under national law, international conventions, treaties or otherwise, and any and all continuations, divisions and renewals of and substitutes for said applications, and in, to and under any and all Letters Patent which may be granted on or as a result thereof in the United States and any and all other countries, and any reissue or reissues or extension or extensions of said Letters Patent, and assign to and authorize said assignee, to file in our name applications for Letters Patent in all countries, the same to be held and enjoyed by said assignee, its successors, assigns, nominees or legal representatives, to the full end of the term or terms for which said Letters Patent respectively may be granted, reissued or extended, as fully and entirely as the same would have been held and enjoyed by me had this assignment,

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**PATENT** 

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Mirai Ref. No.:SINF0111

sale and transfer not been made.

AND We hereby covenant that We have full right to convey the entire interest herein assigned, and that we have not executed and will not execute any agreement in conflict herewith, and we further covenant and agree that we will each time request is made and without undue delay, execute and deliver all such papers as may be necessary or desirable to perfect the title to said inventions or improvements, said application and said Letters Patent to said assignee, its

successors, assigns, nominees, or legal representatives, all known facts respecting said inventions or improvements, said applications and said Letters Patent, to testify in any legal proceedings, to sign all lawful papers, to execute all disclaimers and divisional, continuing, reissue and foreign applications, to make all rightful oaths, and generally to do everything possible to aid said assignee, its successors, assigns, nominees and legal representatives to obtain and enforce for its or their own benefit proper patent protection for said inventions or improvements in any and all countries.

AND We hereby authorize and request the Director – U.S. Patent and Trademark Office and any official of any country or countries foreign to the United States whose duty it is to issue patents on applications as aforesaid, to issue to said assignee, as assignee of the entire right, title and interest, any and all Letters Patent for said inventions or improvements, including any and all Letters Patent of the United States which may be issued and granted on or as a result of the applications aforesaid, in accordance with the terms of this assignment.

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

Dated: oct. 26. 2009 Yoshiaki Kudo (L. S.)

Yoshiaki KUDO, Inventor

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

Dated: 0ct 26 2009 Hakoda Takashi' (L. S.)

Takashi HAKODA, Inventor

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**DOCKET NO.: MIRAI-1001** 

Nissei Ref. No.: SD610 Mirai Ref. No.:SINF0111 **PATENT** 

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

Dated: 0ct. 26.2009

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

Dated: Oct. 26 2009 Susumu Morozumi (L. S.)

Susumu MOROZUMI, Inventor

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**PATENT REEL: 023752 FRAME: 0983**